



BUK9K29-100E

Dual N-channel TrenchMOS logic level FET

28 March 2013

Product data sheet

1. General description

Dual logic level N-channel MOSFET in a LFAK56D package using TrenchMOS technology. This product has been designed and qualified to AEC Q101 standard for use in high performance automotive applications.

2. Features and benefits

- Q101 compliant
- Repetitive avalanche rated
- Suitable for thermally demanding environments due to 175 °C rating
- True logic level gate with $V_{GS(th)} > 0.5 \text{ V @ } 175 \text{ °C}$

3. Applications

- 12 V Automotive systems
- Motors, lamps and solenoid control
- Start-stop micro-hybrid applications
- Transmission control
- Ultra high performance power switching

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25 \text{ °C}; T_j \leq 175 \text{ °C}$	-	-	100	V
I_D	drain current	$V_{GS} = 5 \text{ V}; T_{mb} = 25 \text{ °C}; \text{Fig. 1}$	-	-	30	A
P_{tot}	total power dissipation	$T_{mb} = 25 \text{ °C}; \text{Fig. 2}$	-	-	68	W
T_j	junction temperature		-55	-	175	°C
Static characteristics FET1 and FET2						
R_{DSon}	drain-source on-state resistance	$V_{GS} = 5 \text{ V}; I_D = 5 \text{ A}; T_j = 25 \text{ °C}; \text{Fig. 12}$	-	25.1	29	mΩ
Dynamic characteristics FET1 and FET2						
$Q_{G(tot)}$	total gate charge	$I_D = 10 \text{ A}; V_{DS} = 80 \text{ V}; V_{GS} = 10 \text{ V};$	-	54	-	nC
Q_{GD}	gate-drain charge	$T_j = 25 \text{ °C}; \text{Fig. 14}; \text{Fig. 15}$	-	10.9	-	nC

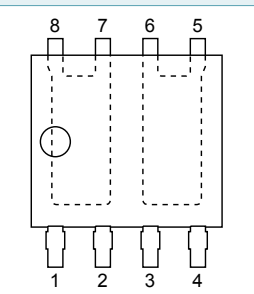
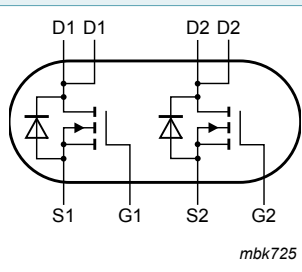


Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Avalanche Ruggedness FET1 and FET2						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$I_D = 30\text{ A}$; $V_{sup} \leq 100\text{ V}$; $V_{GS} = 5\text{ V}$; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; Fig. 3	[1][2]	-	-	83 mJ

- [1] Refer to application note AN10273 for further information
- [2] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S1	source1	 <p>LFPAK56D (SOT1205)</p>	 <p style="text-align: right;"><i>mbk725</i></p>
2	G1	gate1		
3	S2	source2		
4	G2	gate2		
5	D2	drain2		
6	D2	drain2		
7	D1	drain1		
8	D1	drain1		

6. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
BUK9K29-100E	LFPAK56D	Plastic single ended surface mounted package (LFPAK56D); 8 leads	SOT1205

7. Marking

Table 4. Marking codes

Type number	Marking code
BUK9K29-100E	9291E

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25\text{ °C}; T_j \leq 175\text{ °C}$		-	100	V
V_{DGR}	drain-gate voltage	$R_{GS} = 20\text{ k}\Omega; T_j \geq 25\text{ °C}; T_j \leq 175\text{ °C}$		-	100	V
V_{GS}	gate-source voltage	$T_j \leq 175\text{ °C}; \text{DC}$		-10	10	V
		$T_j \leq 175\text{ °C}; \text{Pulsed}$	[1][2]	-15	15	V
I_D	drain current	$T_{mb} = 25\text{ °C}; V_{GS} = 5\text{ V}; \text{Fig. 1}$		-	30	A
		$T_{mb} = 100\text{ °C}; V_{GS} = 5\text{ V}; \text{Fig. 1}$		-	21	A
I_{DM}	peak drain current	$T_{mb} = 25\text{ °C}; \text{pulsed}; t_p \leq 10\text{ }\mu\text{s}; \text{Fig. 4}$		-	118	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}; \text{Fig. 2}$		-	68	W
T_{stg}	storage temperature			-55	175	°C
T_j	junction temperature			-55	175	°C
$T_{sld(M)}$	peak soldering temperature			-	260	°C
Source-drain diode FET1 and FET2						
I_S	source current	$T_{mb} = 25\text{ °C}$		-	30	A
I_{SM}	peak source current	pulsed; $t_p \leq 10\text{ }\mu\text{s}; T_{mb} = 25\text{ °C}$		-	118	A
Avalanche Ruggedness FET1 and FET2						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$I_D = 30\text{ A}; V_{sup} \leq 100\text{ V}; V_{GS} = 5\text{ V}; T_{j(\text{init})} = 25\text{ °C}; \text{Fig. 3}$	[3][4]	-	83	mJ

[1] Accumulated Pulse duration up to 50 hours delivers zero defect ppm

[2] Significantly longer life times are achieved by lowering T_j and or V_{GS} .

[3] Refer to application note AN10273 for further information

[4] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C

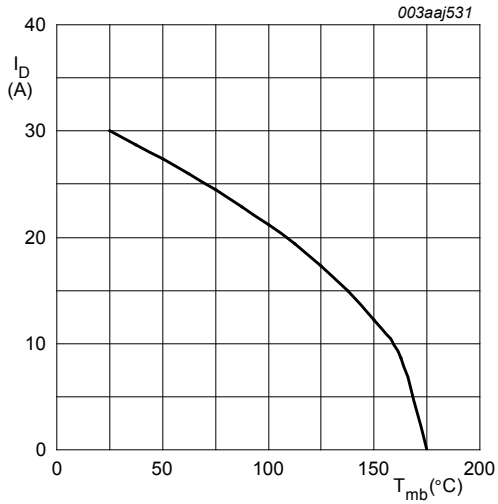


Fig. 1. Continuous drain current as a function of mounting base temperature

$$V_{GS} \geq 5V$$

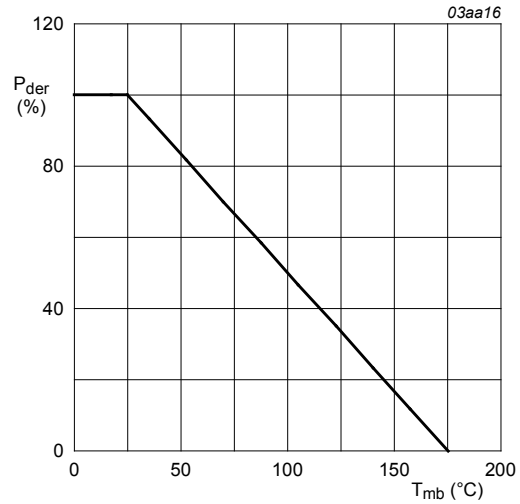


Fig. 2. Normalized total power dissipation as a function of mounting base temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25^\circ C)}} \times 100\%$$

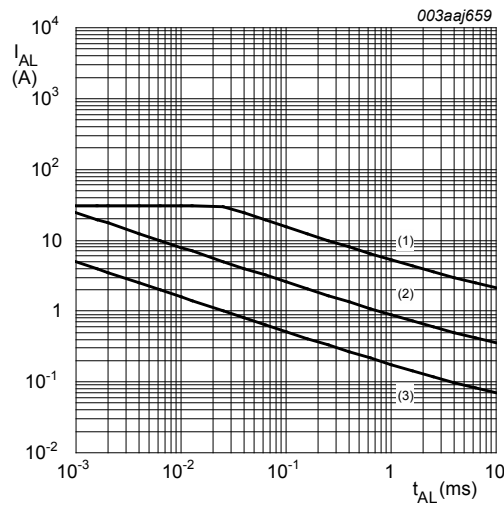
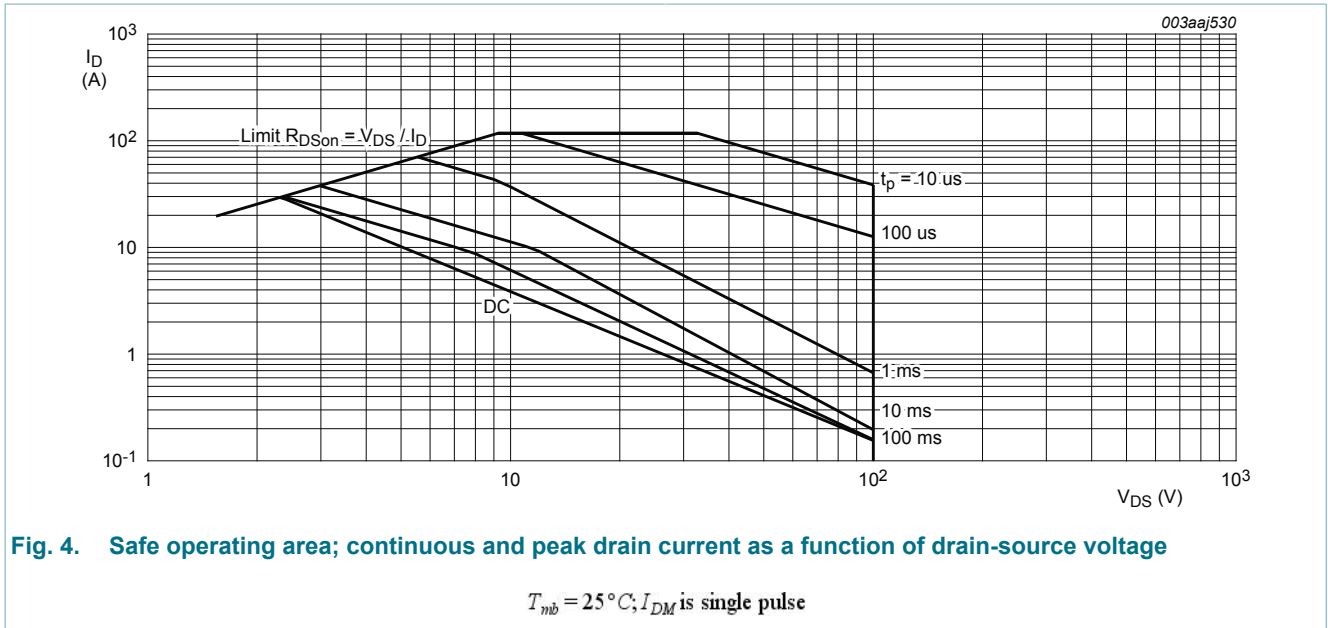


Fig. 3. Single-pulse and repetitive avalanche rating; avalanche current as a function of avalanche time, FET1 and FET2

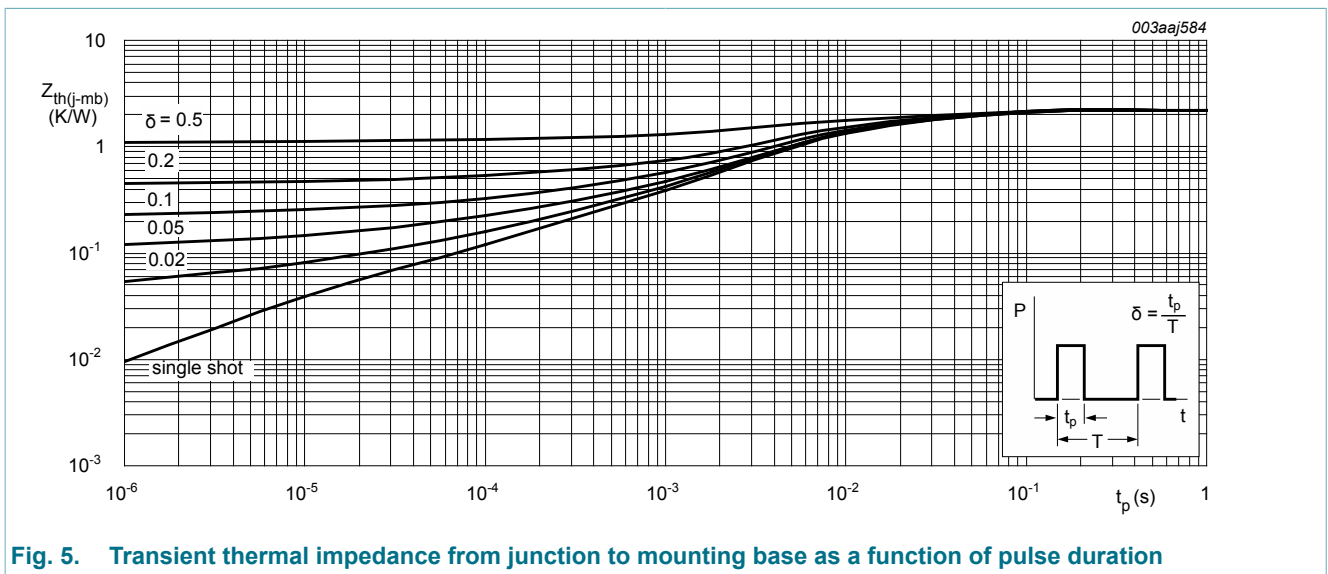
- (1) Single-pulse; $T_j = 25^\circ C$.
- (2) Single-pulse; $T_j = 150^\circ C$.
- (3) Repetitive.



9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 5	-	-	2.21	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	Minimum footprint; mounted on a printed circuit board	-	95	-	K/W



10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics FET1 and FET2						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = -55 \text{ }^\circ C$	90	-	-	V
		$I_D = 250 \mu A; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$	100	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ }^\circ C;$ Fig. 10; Fig. 11	1.4	1.7	2.1	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 175 \text{ }^\circ C;$ Fig. 10; Fig. 11	0.5	-	-	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ }^\circ C;$ Fig. 10; Fig. 11	-	-	2.45	V
I_{DSS}	drain leakage current	$V_{DS} = 100 V; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$	-	0.02	1	μA
		$V_{DS} = 100 V; V_{GS} = 0 V; T_j = 175 \text{ }^\circ C$	-	-	500	μA
I_{GSS}	gate leakage current	$V_{GS} = -10 V; V_{DS} = 0 V; T_j = 25 \text{ }^\circ C$	-	2	100	nA
		$V_{GS} = 10 V; V_{DS} = 0 V; T_j = 25 \text{ }^\circ C$	-	2	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 5 V; I_D = 5 A; T_j = 25 \text{ }^\circ C;$ Fig. 12	-	25.1	29	m Ω
		$V_{GS} = 5 V; I_D = 5 A; T_j = 175 \text{ }^\circ C;$ Fig. 12; Fig. 13	-	68.02	80	m Ω
		$V_{GS} = 10 V; I_D = 5 A; T_j = 25 \text{ }^\circ C;$ Fig. 12	-	22.7	27	m Ω
Dynamic characteristics FET1 and FET2						
$Q_{G(tot)}$	total gate charge	$I_D = 10 A; V_{DS} = 80 V; V_{GS} = 10 V;$ $T_j = 25 \text{ }^\circ C;$ Fig. 14; Fig. 15	-	54	-	nC
Q_{GS}	gate-source charge	$I_D = 10 A; V_{DS} = 80 V; V_{GS} = 10 V;$ $T_j = 25 \text{ }^\circ C;$ Fig. 15; Fig. 14	-	5.6	-	nC
Q_{GD}	gate-drain charge	$I_D = 10 A; V_{DS} = 80 V; V_{GS} = 10 V;$ $T_j = 25 \text{ }^\circ C;$ Fig. 14; Fig. 15	-	10.9	-	nC
C_{iss}	input capacitance	$V_{GS} = 0 V; V_{DS} = 25 V; f = 1 \text{ MHz};$ $T_j = 25 \text{ }^\circ C;$ Fig. 16	-	2727	3637	pF
C_{oss}	output capacitance		-	169	203	pF
C_{rss}	reverse transfer capacitance		-	106	145	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 80 V; R_L = 8 \Omega; V_{GS} = 10 V;$ $R_{G(ext)} = 5 \Omega; T_j = 25 \text{ }^\circ C; I_D = 10 A$	-	6.1	-	ns
t_r	rise time		-	6.4	-	ns
$t_{d(off)}$	turn-off delay time		-	67.3	-	ns
t_f	fall time		-	35.1	-	ns
Source-drain diode FET1 and FET2						
V_{SD}	source-drain voltage	$I_S = 15 A; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C;$ Fig. 17	-	0.78	1.2	V

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_{rr}	reverse recovery time	$I_S = 10 \text{ A}$; $dI_S/dt = -100 \text{ A}/\mu\text{s}$; $V_{GS} = 0 \text{ V}$;	-	32.7	-	ns
Q_r	recovered charge	$V_{DS} = 50 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$	-	50.1	-	nC

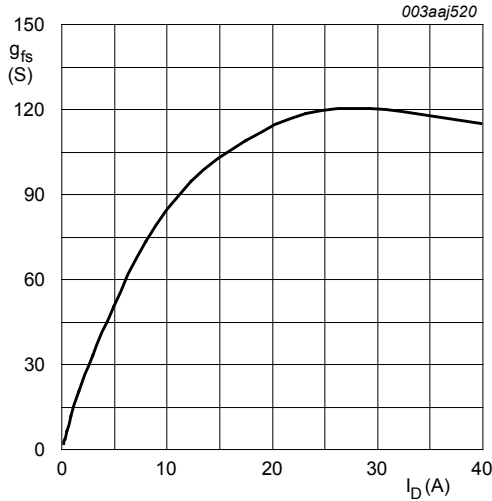


Fig. 6. Forward transconductance as a function of drain current; typical values

$T_j = 25 \text{ }^\circ\text{C}$; $V_{DS} = 15 \text{ V}$

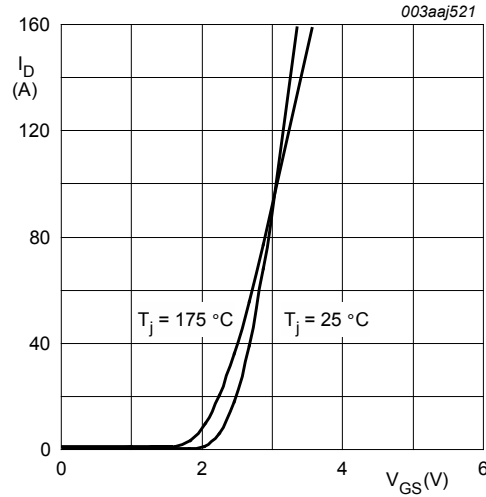


Fig. 7. Transfer characteristics: drain current as a function of gate-source voltage; typical values

$V_{DS} = 10 \text{ V}$

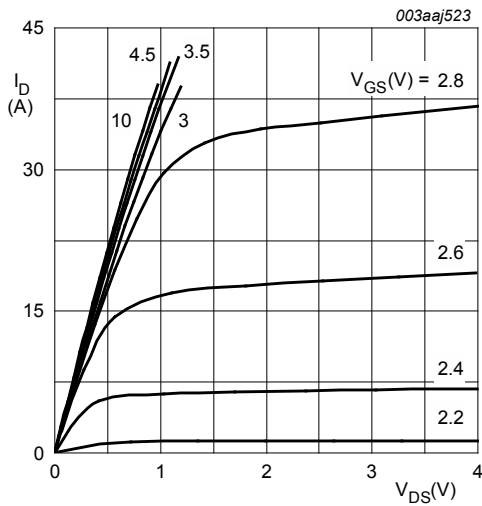


Fig. 8. Output characteristics: drain current as a function of drain-source voltage; typical values

$T_j = 25 \text{ }^\circ\text{C}$

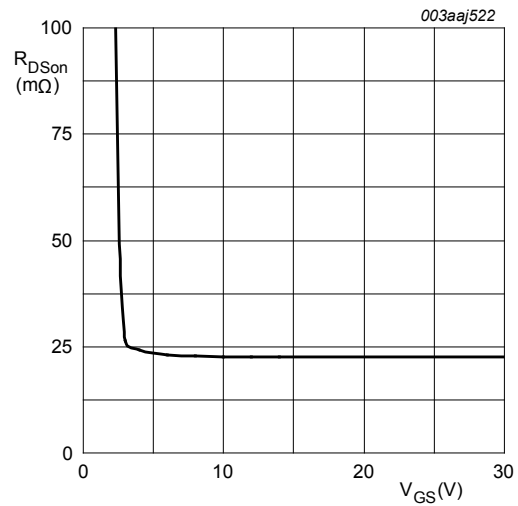


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

$T_j = 25 \text{ }^\circ\text{C}$; $I_D = 5 \text{ A}$

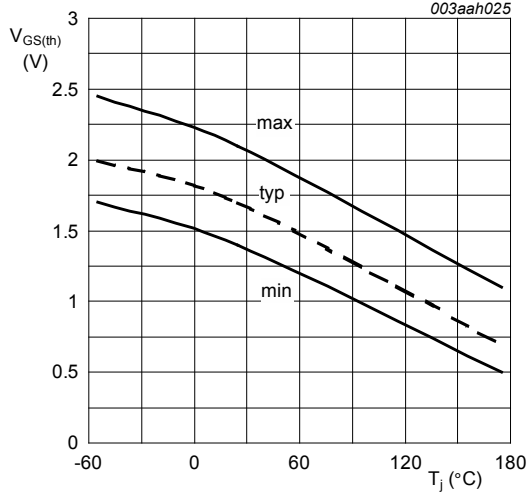


Fig. 10. Gate-source threshold voltage as a function of junction temperature

$$I_D = 1 \text{ mA}; V_{DS} = V_{GS}$$

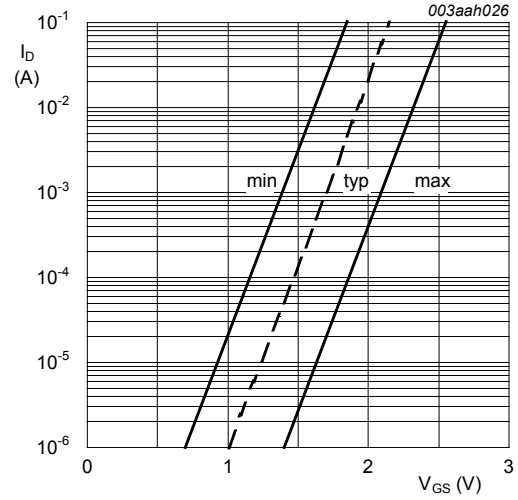


Fig. 11. Sub-threshold drain current as a function of gate-source voltage

$$T_j = 25^\circ\text{C}; V_{DS} = 5\text{V}$$

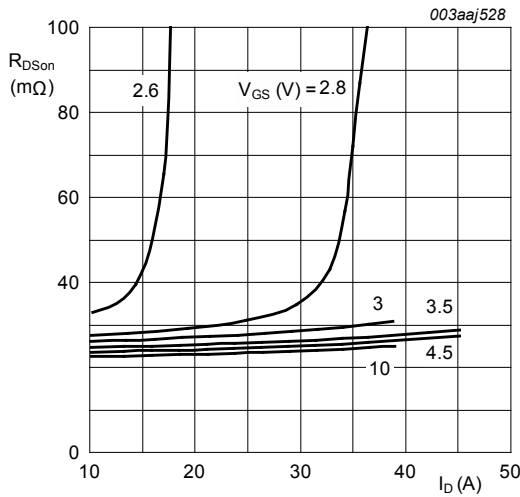


Fig. 12. Drain-source on-state resistance as a function of drain current; typical values

$$T_j = 25^\circ\text{C}$$

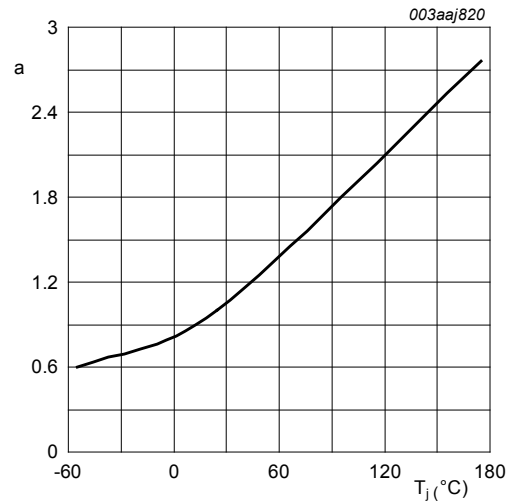


Fig. 13. Normalized drain-source on-state resistance factor as a function of junction temperature

$$a = \frac{R_{DS(on)}}{R_{DS(on)}(25^\circ\text{C})}$$

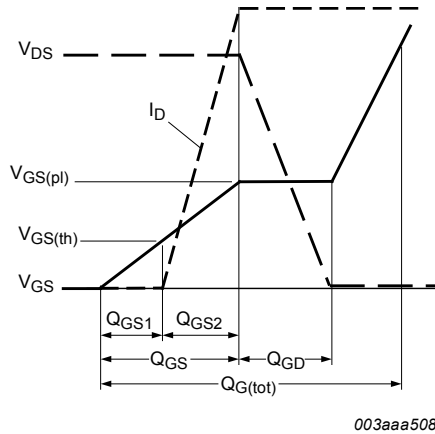


Fig. 14. Gate charge waveform definitions

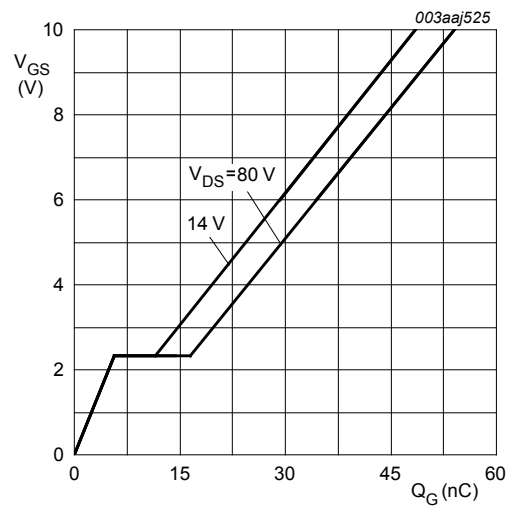


Fig. 15. Gate-source voltage as a function of gate charge; typical values

$T_j = 25^\circ\text{C}; I_D = 10\text{A}$

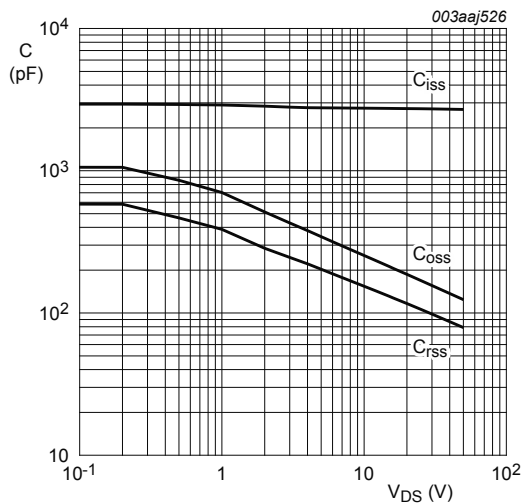


Fig. 16. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

$V_{GS} = 0\text{V}; f = 1\text{MHz}$

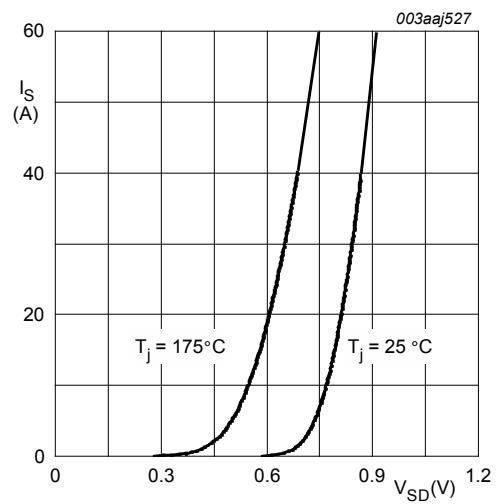


Fig. 17. Source current as a function of source-drain voltage; typical values

$V_{GS} = 0\text{V}$

11. Package outline

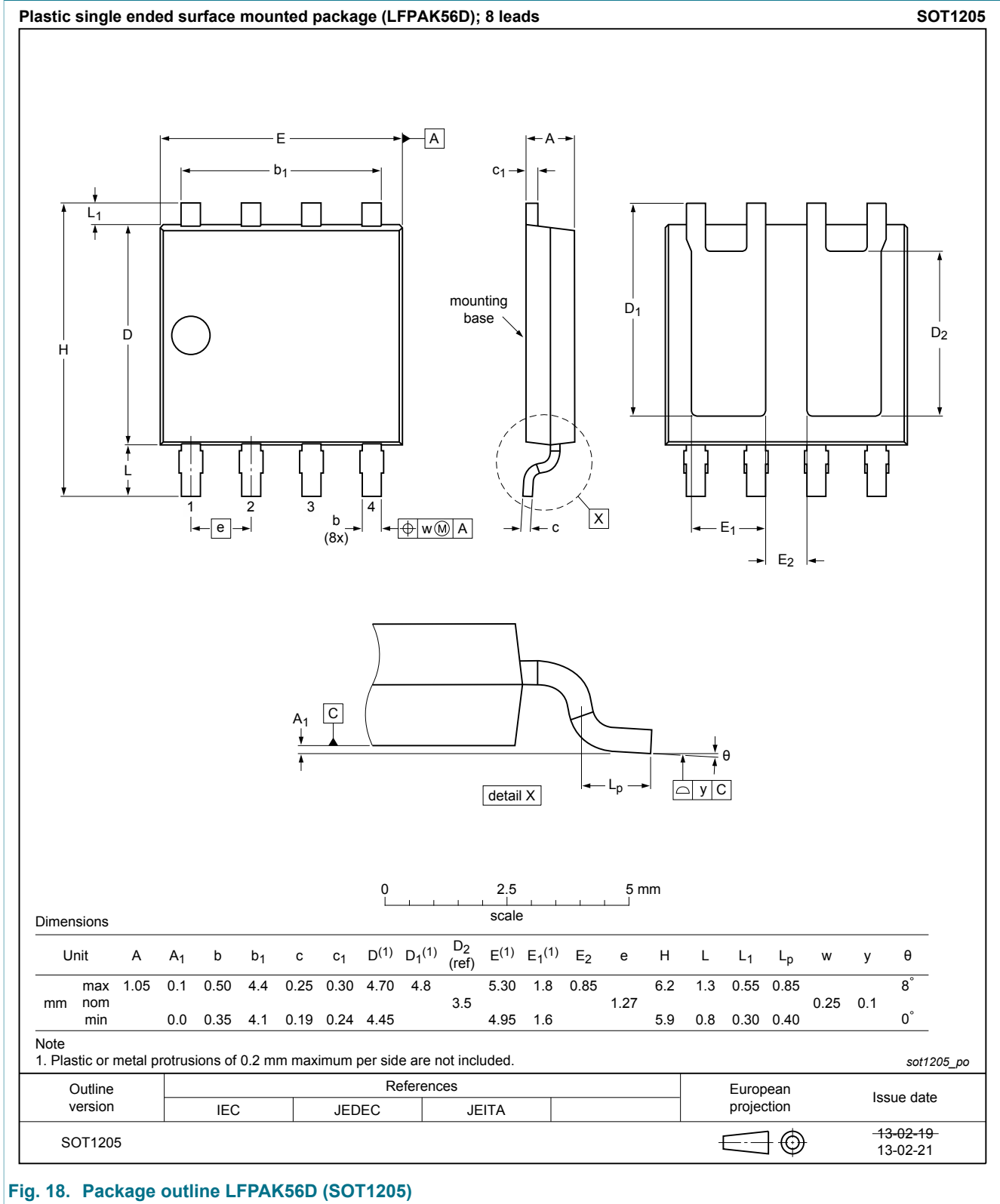


Fig. 18. Package outline LPAK56D (SOT1205)

12. Legal information

12.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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Date of release: 28 March 2013